

Product / Package Information

Package	SOIC_W
Body Size	300 mils
Lead Count	16
Terminal Finish	100Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	No
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.58 E-01	86.20	862000	57.27	572719
Thermosets	Epoxy resin	Proprietary	2.25 E-02	7.50	75000	4.98	49831
Thermosets	Phenol Novolac	9003-35-4	1.20 E-02	4.00	40000	2.66	26576
Other inorganic materials	Antimony Trioxide	1309-64-4	4.49 E-03	1.50	15000	1.00	9966
Thermosets	Brominated Resin	40039-93-8	1.50 E-03	0.50	5000	0.33	3322
Other inorganic materials	Carbon Black	1333-86-4	8.99 E-04	0.30	3000	0.20	1993
Subtotal			3.00 E-01	100	1000000	66.44	664408

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.37 E-01	97.57	975706	30.33	303342
Copper & its alloys	Iron	7439-89-6	3.19 E-03	2.28	22789	0.71	7085
Copper & its alloys	Zinc	7440-66-6	1.77 E-04	0.13	1263	0.04	393
Copper & its alloys	Phosphorus	7723-14-0	3.40 E-05	0.02	242	0.01	75
Subtotal			1.40 E-01	100.00	1000000	31.09	310895

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.42 E-03	100.0	1000000	0.31	3140

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	4.72 E-03	100.0	1000000	1.05	10465

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	5.00 E-04	99.99	1000000	0.11	1109

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	3.99 E-03	100.0	1000000	0.89	8851

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.08 E-04	80	800000	0.09	905
Thermosets	Epoxy Resin	Proprietary	7.65 E-05	15	150000	0.02	170
Others	Curing agent & hardener	Proprietary	2.55 E-05	5	50000	0.01	57
Subtotal			5.10 E-04	100	1000000	0.11	1131

Package Totals	Weight (g)	Percentage (%)	PPM
	4.51 E-01	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge
 ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability
 any inaccuracy of such information.



ADI Proprietary

Product / Package Information

Package	SOIC_W
Body Size	300 mils
Lead Count	16
Terminal Finish	SnPb

Environmental Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	No
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.58 E-01	86.2	862000	57.25	572491
Thermosets	Epoxy resin	Proprietary	2.25 E-02	7.5	75000	4.98	49811
Thermosets	Phenol Novolac	9003-35-4	1.20 E-02	4	40000	2.66	26566
Other inorganic materials	Antimony Trioxide	1309-64-4	4.49 E-03	1.5	15000	1.00	9962
Thermosets	Brominated Resin	40039-93-8	1.50 E-03	0.5	5000	0.33	3321
Other inorganic materials	Carbon Black	1333-86-4	8.99 E-04	0.3	3000	0.20	1992
Subtotal			3.00 E-01	100	1000000	66.41	664143

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.37 E-01	97.57	975706	30.32	303221
Copper & its alloys	Iron	7439-89-6	3.19 E-03	2.28	22789	0.71	7082
Copper & its alloys	Zinc	7440-66-6	1.77 E-04	0.13	1263	0.04	382
Copper & its alloys	Phosphorus	7723-14-0	3.40 E-05	0.02	242	0.01	75
Subtotal			1.40 E-01	100.00	1000000	31.08	310771

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.42 E-03	100.0	1000000	0.31	3139

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	4.01 E-03	85.0	850000	0.89	8891
Tin & its alloys	Lead	7439-92-1	7.08 E-04	15.0	150000	0.16	1569
Subtotal			4.72 E-03	100.0	1000000	1.05	10460

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	5.00 E-04	99.99	1000000	0.11	1109

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	3.99 E-03	100.0	1000000	0.88	8848

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.08 E-04	80	800000	0.09	905
Thermosets	Epoxy Resin	Proprietary	7.65 E-05	15	150000	0.02	170
Others	Curing agent & hardener	Proprietary	2.55 E-05	5	50000	0.01	57
Subtotal			5.10 E-04	100	1000000	0.11	1131

Die Coat

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Dimethylsiloxane	68083-19-2	1.09 E-04	60.4	604000	0.02	241
Other organic materials	Dimethylvinylated & Trimethylated silicic	68988-89-6	5.04 E-05	28.0	280000	0.01	112
Other organic materials	Dimethyl, Methylhydrogen siloxane	68037-59-2	1.80 E-05	10.0	100000	0.00	40
Other organic materials	Ethylbenzene	100-41-4	1.80 E-06	1.0	10000	0.00	4
Other organic materials	Xylene	1330-20-7	1.08 E-06	0.6	6000	0.00	2
Subtotal			1.80 E-04	100.0	1000000	0.04	399

Package Totals			Weight (g)	4.51 E-01		Percentage (%)	100.00	PPM	1000000
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 any inaccuracy of such information.



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